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| **Step** | **Process description** | **Cross-section after process** |
| **01** | Substrate: Clean Si wafer |  |
| **02** | Substrate oxidation (2um SiO2) |  |
| **03** | Spin coating of photo-resist |  |
| **04** | Metrology of the thickness (optical with filmetrics or ellipsometer) |  |
| **05** | Photolithography |  |
| **06** | Development of the resist |  |
| **07** | Thin film deposition with evaporation | C:\Users\AJOLLIVE\Desktop\Travail\EPFL\CMI\Task lists\VRC\P4.png |
| **08** | Resist stripping (lift-off) |  |
| **09** | Metrology of the thickness (mechanical AFM or profilometer) |  |